L Number	Hits	Search Text	DB	Time stamp
-	21	"non-key" and semiconductor	USPAT;	2004/04/27
			US-PGPUB;	11:33
			EPO; JPO;	
			DERWENT	·
l _	12	5,978,807	USPAT;	2004/04/27
]	3,3,0,007	US-PGPUB;	14:36
			EPO; JPO;	11.30
			DERWENT	
_	2	"common tool set capacity"	USPAT;	2004/04/27
_		common tool set capacity	US-PGPUB;	14:36
			EPO; JPO;	14.30
			DERWENT	
_	1	"common tool set" and semiconductor	USPAT;	2004/04/27
-	1	Common tool set and semiconductor	US-PGPUB;	14:37
			EPO; JPO;	14.57
			DERWENT	:
	605			2004/04/27
-	605	l + -	USPAT;	2004/04/27
	1	semiconductor and calculating	US-PGPUB;	14:2/
			EPO; JPO;	•
		/	DERWENT	2004/04/27
-	5	(capacity and overall and wafer and	USPAT;	2004/04/27
		semiconductor and calculating) and	US-PGPUB;	14:50
		"overall capacity" and dividing	EPO; JPO;	
			DERWENT	
-	2	"capacity consumption factor"	USPAT;	2004/04/27
			US-PGPUB;	14:51
			EPO; JPO;	
			DERWENT	
-	15	"5946212"	USPAT;	2004/04/27
			US-PGPUB;	14:53
			EPO; JPO;	
			DERWENT	1
-	1		USPAT	2004/04/27
				14:51
-	1		USPAT	2004/04/27
				14:51
-	1		USPAT	2004/04/27
	İ			14:52
-	20	"capacity planning" and technologies and	USPAT;	2004/04/27
1		"tool sets"	US-PGPUB;	15:21
			EPO; JPO;	1
			DERWENT	
-	26	"technology based" and "design based" and	USPAT;	2004/04/27
		semiconductor	US-PGPUB;	15:30
			EPO; JPO;	1
			DERWENT	:
-	632	fabricator and technology and design	USPAT;	2004/04/27
		· · ·	US-PGPUB;	15:30
			EPO; JPO;	:
			DERWENT	
-	11	(fabricator and technology and design)	USPAT;	2004/04/27
1		and organizing	US-PGPUB;	15:31
		J	EPO; JPO;	
]			DERWENT	1
_	210	(fabricator and technology and design)	USPAT;	2004/04/27
		and wafer	US-PGPUB;	15:31
			EPO; JPO;	
	1		DERWENT	1
	l	<u> </u>	Lanimani	1